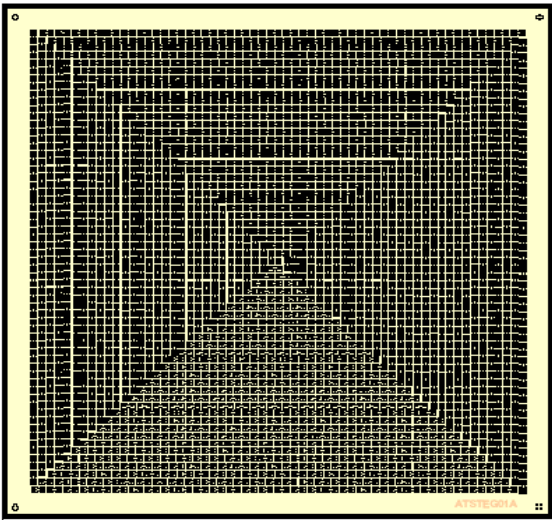
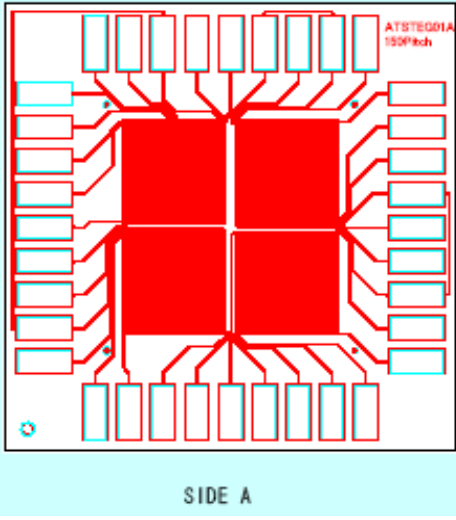




ATSTEG01A

CHIP	ATS-TEG01A		
Layout	チップ ATSTEG01A 10mm /150μmピッチ		
			
Name	ATS-TEG01A_CC	ATS-TEG01A_LF	ATS-TEG01A_EU
Bump Metal	High Lead	Lead Free	Eutectic
Bumping Process	Ball mount		
Wafer Size	8		
Base Chip Size	10mm*10mm		
Pad Pitch	150μm(AREA)		
Options	Back Graind >50um Dicing		

Kit-PCB	ATSTEG-150
Layout	評価基板 10mm /20mm
	
Conformed	Side-A (Only)
Chip	ATS-TEG01A
Chip Size	10.00mm , 20.00mm
Bumps	Solder Bump
Bump Layout	150μm/AREA
Number of Bumps	Max.14884 Bumps
PCB Material	High Tg FR-4(Hitachi Chemical E697)
SIZE	40.0mm x 40.0mm x 0.65mm (t)



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